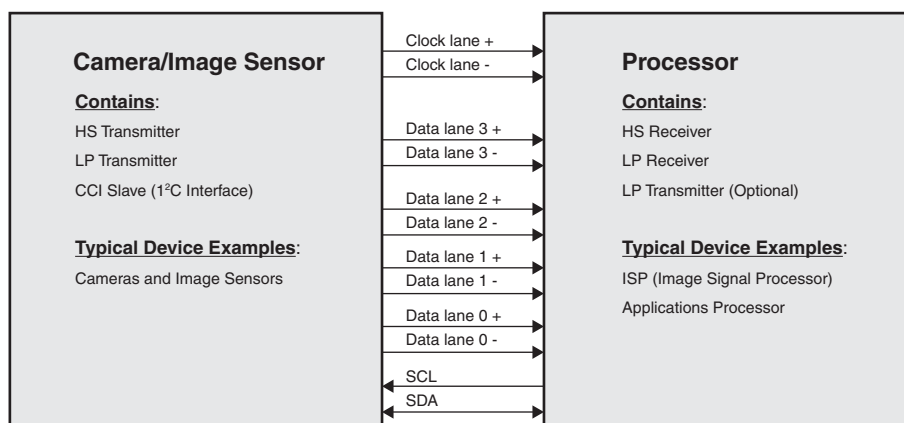


## Introduction

The Mobile Industry Processor Interface (MIPI) has become a specification standard for interfacing components in consumer mobile devices. The MIPI Camera Serial Interface 2 (CSI-2) specification provides a protocol layer interface definition, which is used to interface with Cameras and Image Sensors. The Parallel to MIPI CSI-2 TX Bridge Reference Design allows users to deliver data to a MIPI CSI-2 compatible receiver such as an ISP (Image Signal Processor) from a standard parallel video interface. See Figure 1.

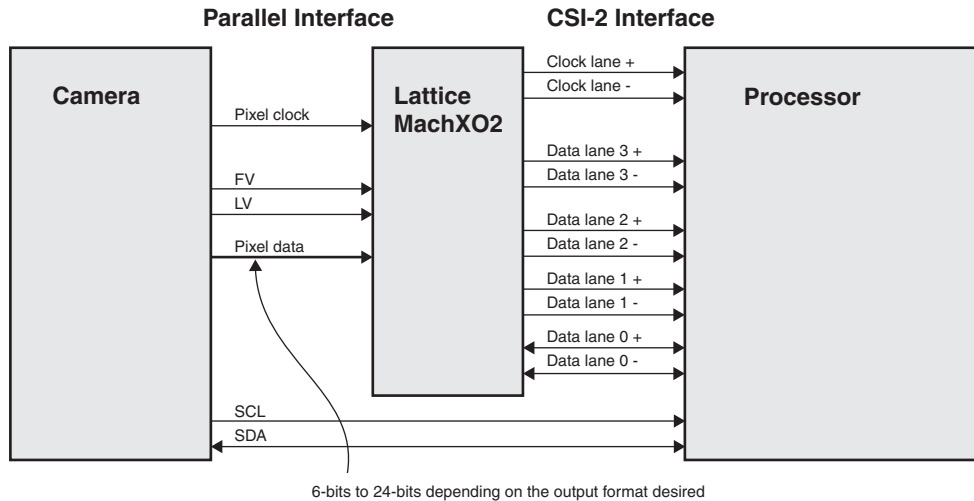
**Figure 1. CSI-2 Interface**



## Key Features

- Interfaces to MIPI CSI-2 Receiving Devices
- Supports Unidirectional HS (High Speed) Mode
- Supports Bidirectional LP (Low Power) Mode
- Serializes HS (High Speed) data from up to four data lanes
- Supports all CSI-2 compatible video formats (RAW, YUV, RGB and User Defined)

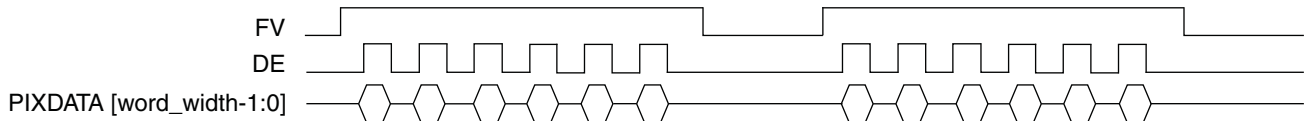
**Figure 2. Parallel to MIPI CSI-2 TX Bridge**



## Functional Description

The Parallel to MIPI CSI-2 TX Bridge Reference Design converts a standard parallel video interface into CSI-2 byte packets. It then serializes HS data and controls LP (Low Power) and HS (High Speed) data transfers using the Lattice RD1182, [MIPI D-PHY Reference IP](#). The input interface for the design consists of a data bus (PIXDATA), line and frame valid indicators (FV and LV) and a clock (PIXCLK). The output interface consists of HS and LP signals that must be connected together using an external resistor network, which is described in the [Unidirectional Transmit HS Mode and Bidirectional LP Mode Interface Implementation](#) section of this document. Further information regarding this resistor network can also be found in the Lattice RD1182, [MIPI D-PHY Reference IP](#) documentation. HS and LP signals for the clock lane and data lanes are provided on DCK, D0, D1, D2, D3 and LPCLK, LP0, LP1, LP2, and LP3 signals respectively. Include parameters control the amount of data ports available for HS and LP modes at the top level depending on the number of data lanes used.

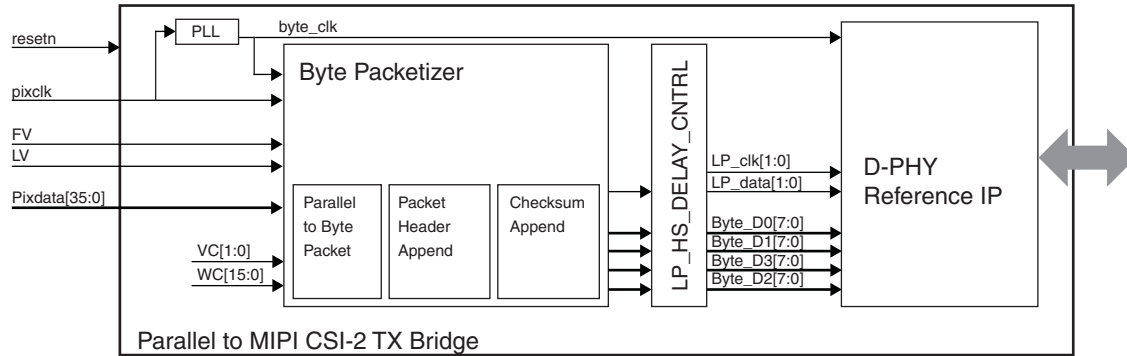
**Figure 3. Bridge Input Signal Format**



The top level design (top.v) consists of five modules:

- byte\_packetizer.v – Converts parallel data to byte packets. Appends Packet Header and Checksum.
- lp\_hs\_dly\_ctrl.v – Controls time delay between clock and data lanes when entering and exiting HS mode. Controls time delay from when HS mode is entered to when data is placed on the data bus.
- dphy\_tx\_inst.v – Serializes byte data using iDDR4 gearbox primitives. Controls high impedance and bi-directional states of HS and LP signals.
- pll\_pix2byte\_gen.v – Converts pixel clock to HS clock and byte clocks. Output frequencies depend on input clock, input bus width and number of MIPI data lanes.
- colorbar\_gen.v – Pattern generator capable of generating a colorbar or walking 1's pattern.

**Figure 4. Top Level Block Diagram**



To control the ports defined at the top level, `define compiler directives are used. These compiler directives can be found in compiler\_directives.v

**Table 1. Compiler Directives Defined in compiler\_directives.v**

| Directive      | Description  |
|----------------|--|
| `define HS_3   | Generates IO for four HS data lanes.   |
| `define HS_2   | Generates IO for three HS data lanes. Overridden if HS_3 is defined.             |
| `define HS_1   | Generates IO for two HS data lanes. Overridden if HS_3 or HS_2 is defined.       |
| `define HS_0   | Generates IO for one HS data lane. Overridden if HS_3, HS_2, or HS_1 is defined. |
| `define LP_CLK | Generates IO for LP mode on clock lane   |
| `define LP_0   | Generates IO for LP mode on data lane 0  |
| `define LP_1   | Generates IO for LP mode on data lane 1  |
| `define LP_2   | Generates IO for LP mode on data lane 2  |
| `define LP_3   | Generates IO for LP mode on data lane 3  |

Design parameters control other features of the design. These design parameters are located at the top of the module declaration in top.v.

**Table 2. Top Level Module Parameters**

| Parameter  | Options                     | Description  |
|------------|-----------------------------|--|
| VC         | 2-bit Virtual Channel value | Virtual Channel number appended to the Packet Header   |
| WC         | 16-bit Word Count value     | Word Count number appended to the Packet Header. Correlates to the number of bytes to be transferred in a Long Packet.               |
| word_width | Up to 36 bits               | Bus width of pixel data bus input  |
| DT         | 6-bit Data Type Value       | Data Type appended to Packet Header for Long Packet transfers  |
| testmode   | 0 = off<br>1 = on           | Adds colorbar pattern generator for testing purposes. Pattern generator utilizes reset_n and PIXCLK.                                 |
| crc16      | 0 = off<br>1 = on           | Appends checksum after Long Packet transfers. Turning off will reduce resource utilization and append 16'hFFFF in place of checksum. |

Top level IO ports are defined as follows for top.v. The number of IO is dependent on the number of data lanes defined by compiler\_directives.v.

**Table 3. Top Level Design Port List**

| Signal       | Direction     | Description   |
|--------------|---------------|---|
| reset_n      | Input         | Resets module (Active 'low')                        |
| DCK          | Output        | HS (High Speed) Clock                               |
| D0           | Output        | HS Data lane 0                                      |
| D1           | Output        | HS Data lane 1                                      |
| D2           | Output        | HS Data lane 2                                      |
| D3           | Output        | HS Data lane 3                                      |
| LPCLK [1:0]  | Bidirectional | LP clock lane; LPCLK[1] = P wire, LPCLK[0] = N wire |
| LP0 [1:0]    | Bidirectional | LP data lane 0; LP0[1] = P wire, LP0[0] = N wire    |
| LP1 [1:0]    | Bidirectional | LP data lane 1; LP1[1] = P wire, LP1[0] = N wire    |
| LP2 [1:0]    | Bidirectional | LP data lane 2; LP2[1] = P wire, LP2[0] = N wire    |
| LP3 [1:0]    | Bidirectional | LP data lane 3; LP3[1] = P wire, LP3[0] = N wire    |
| PIXCLK       | Input         | Parallel Pixel Clock                                |
| FV           | Input         | Parallel Data Frame Valid Indicator                 |
| LV           | Input         | Parallel Data Line Valid Indicator                  |
| PIXDATA[*:0] | Input         | Parallel Data Bus                                   |

The top level module instantiates and connects five main modules. In addition, a PLL module controls clocking for the entire design. The input of the PLL is pixel clock. The PLL outputs two high speed oDDRx4 gearbox clocks (0 degree and one with 90 degree phase shifts), the byte clock and the CRC clock.

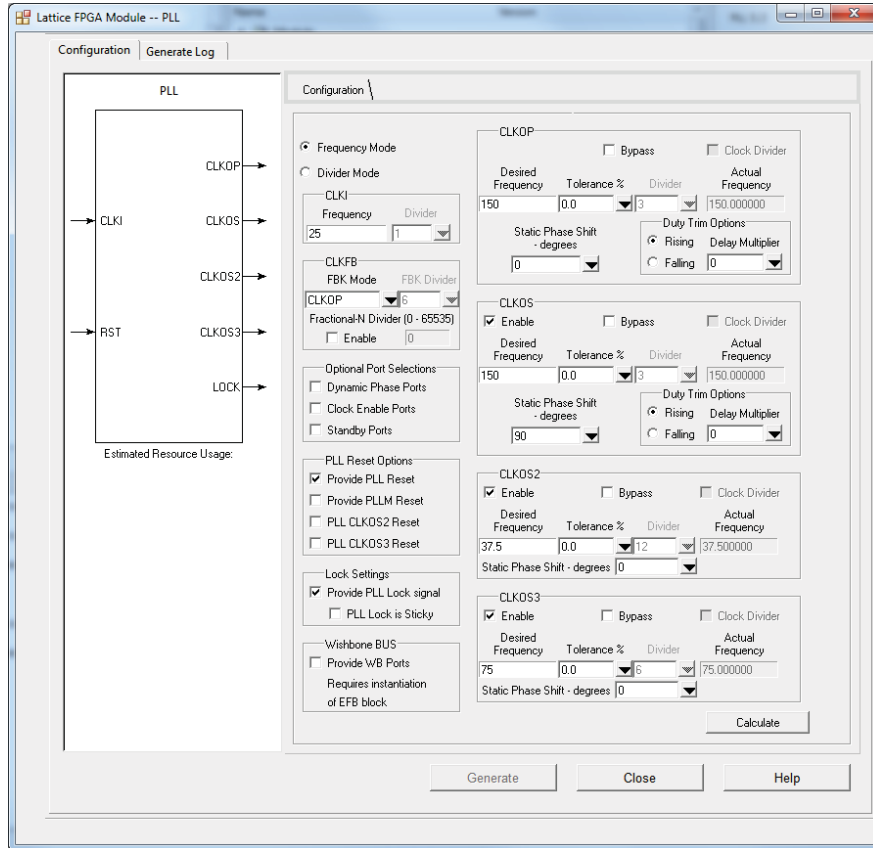
The clock equations for PLL output ports are shown in Table 4.

**Table 4. Clocking for the PLL Output Ports**

| PLL Module Port Name | Clock description                      | Clock Equation   |
|----------------------|--|--|
| CLKI                 | PLL Input                              | CLKI   |
| CLKOP                | oDDRx4 gearbox Clock                   | $CLKOP = CLKI * word\_width / (8 * lane\_width) * 4$     |
| CLKOS                | oDDRx4 gearbox Clock (90 degree shift) | Same as CLKOP, but with static phase shift of 90 degrees |
| CLKOS2               | Byte Clock                             | $CLKOS2 = CLKI * word\_width / (8 * lane\_width)$        |

The PLL is configured using IPExpress in the Lattice Diamond® Software. The PLL comes pre-configured for the appropriate clock conversion ratios based on the mode and number of MIPI data lanes used. It can also be adjusted and reconfigured to individual design needs by double clicking on pll\_pix2byte.ipx in the file list. An IPExpress configuration GUI will open to adjust the PLL.

Figure 5. IPExpress Configuration Page for pll\_pix2byte.ipx:



## BYTE\_PACKETIZER Module Description:

The Byte\_Packetizer module converts pixels to one to four bytes depending on the number of MIPI data lanes defined. The input interface to the module is the pixel data bus. Pixel data is formatted from MSB to LSB for RAW and YUV data types. The RGB data type is formatted as R, then G, then B from MSB to LSB respectively. Additional, input ports include the byte clock and CRC clock. The virtual channel number and word count are also available as interface ports. These ports are clocked into a register on the rising edge and falling edges of FV as well as the rising edge of LV and appended to the Packet Header. By default, the reference design controls the Virtual Channel and Word Count ports through VC and WC parameters in top.v. However, the user can dynamically control VC and WC if desired.

Parameters for the BYTE\_PACKETIZER include word\_width (bus width of the pixel bus), lane\_width (number of byte lanes), dt (data type), crc16 enable. Different NGOs in the \*/NGO/\* folder are called depending on the mode defined.

Within the module the pixel data is converted to bytes. If the data is going to be a long packet, identified by LV (Line Valid), the CRC checksum will be calculated over the data and appended to the end of the long packet. Also appended to the data stream in this module is the Packet Header for all packet types.

The number of horizontal pixels the LV (Line Valid) is high should correlate to an integer multiple of the number of bytes used at the output. It is recommend that active lines be truncated or extended to meet this criteria. This will ensure proper readout of all pixels and a correct checksum calculation.

To ensure that the input pixel data is an integer multiple of the output byte data, the following equation can be used. The LV must be held for an integer number of byte clocks. If "number of byte clocks" does not calculate to an integer value, adjust the number of pixel clock cycles for which LV is active.

$$\text{number of byte clocks} = [(\text{number of pixels}) * (\text{bits per pixel})] / [8 \text{ bits} * (\text{number of data lanes})]$$

Output ports for the BYTE\_PACKETIZER module include the 8-bit data buses for each lane and an enable signal. The hs\_en signal goes active 'high' when any short packet or long packet is to be transmitted.

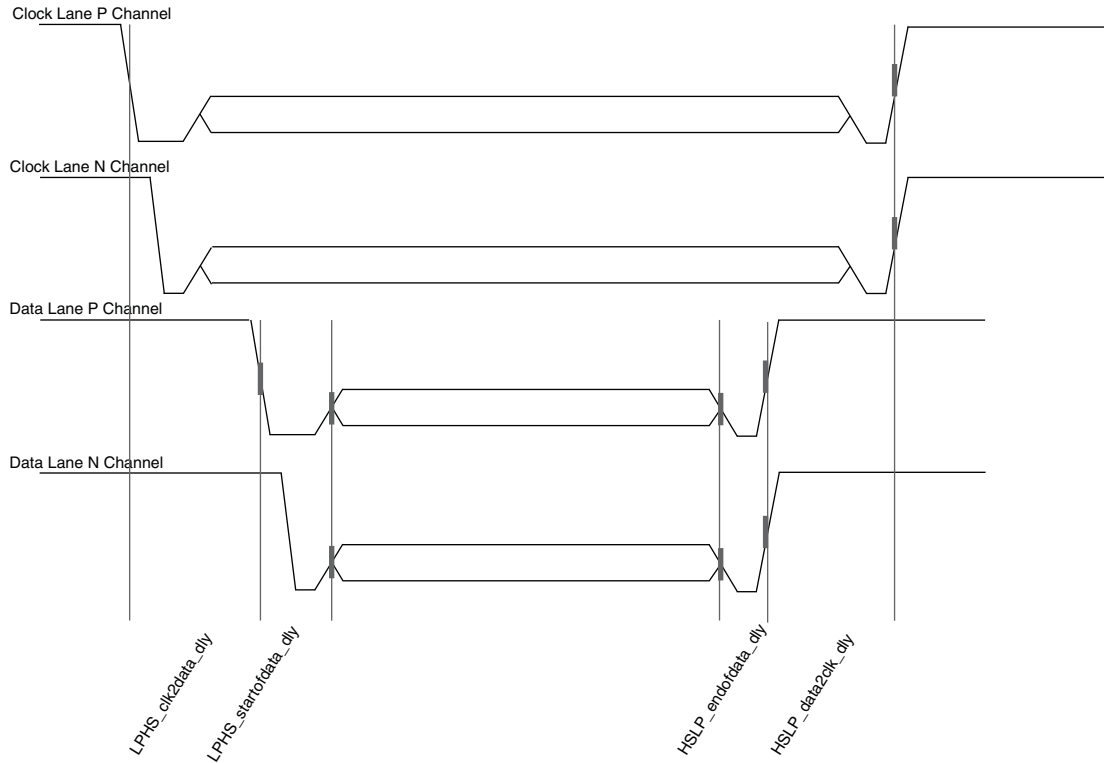
## LP\_HS\_DELAY\_CNTRL Module Description:

The LP\_HS\_DELAY\_CNTRL module uses the hs\_en input from the BYTE\_PACKETIZER and adds delays so that it is ready for transmission. There are controllable delay parameters available in the module header. These control the time delay between when the clock lane and data lanes transition from LP to HS mode as well as from HS mode to LP mode. It also controls when the data starts with respect to when it entered LP mode. LP11-LP01-LP00 transitions are also controlled with one byte clock between transitions. This module is open source and available for any user modifications desired in Lattice FPGA devices.

**Table 5. LP\_HS\_DELAY\_CNTRL Module Parameters**

| Parameter            | Description  |
|----------------------|--|
| LPHS_clk2data_dly    | Number of clocks to delay between the MIPI clock lane and MIPI data lanes transitioning from LP to HS mode |
| LPHS_startofdata_dly | Number of clocks to delay the MIPI data from the LP to HS mode transition                                  |
| HSLP_data2clk_dly    | Number of clocks to delay the HS to LP mode transition between the MIPI data lanes and MIPI clock lane     |
| HSLP_endofdata_dly   | Number of clocks to delay the MIPI data from the HS to LP mode transition                                  |
| sizeofstartcntr      | Size for the start timer counter. Number of bits to count LPHS_clk2data_dly+LPHS_startofdata_dly           |
| sizeofendcntr        | Size for the end timer counter. Number of bits to count HSLP_data2clk_dly+HSLP_endofdata_dly               |

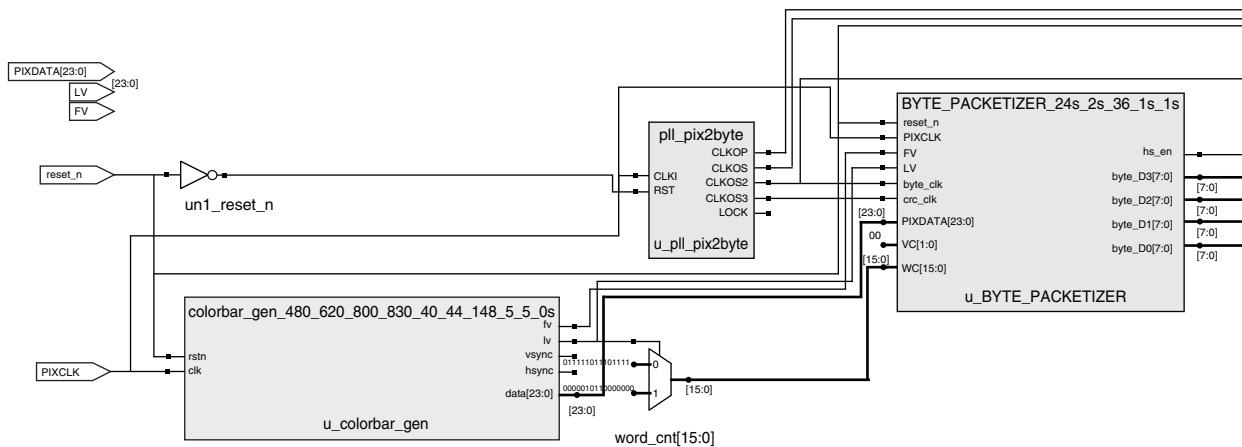
**Figure 6. Timing Diagram for LP\_HS\_DELAY\_CNTRL Delay Parameters**



## Test Mode and colorbar\_gen Module Description:

This reference design also includes a colorbar pattern generator. This allows the user to initially control and drive a display panel with minimal external controls needed from the receiving side. The design is placed in test mode setting the top level design parameter `testmode = 1`. When this is set an additional module `colorbar_gen` is instantiated at the top level and takes over the all input controls (FV, LV and PIXDATA) with the exception of `reset_n` and `PIXCLK`.

**Figure 7. RTL Block Diagram of colorbar\_gen Instantiation When testmode=1:**



## Packaged Design

The Parallel to MIPI CSI-2 TX Bridge Reference Design is available for Lattice MachXO2™ devices. The reference design immediately available on [latticesemi.com](http://latticesemi.com) is configured for RAW10, 2-lane mode. Other designs are available through the bridge request form. The packaged design contains a Lattice Diamond project within the \*impl\ folder configured for the MachXO2 device. Verilog source is contained within the \*rtl\ folder. The Verilog test bench is contained within the tb folder. The simulation folder contains an Aldec Active-HDL project. It is recommended that users access the active HDL Simulation environment through the Lattice Diamond Software and the simulation setup script contained within the project. For details on how to access the design simulation environment see the [Functional Simulation](#) section of this document.

**Figure 8. Packaged Design Directory Structure**

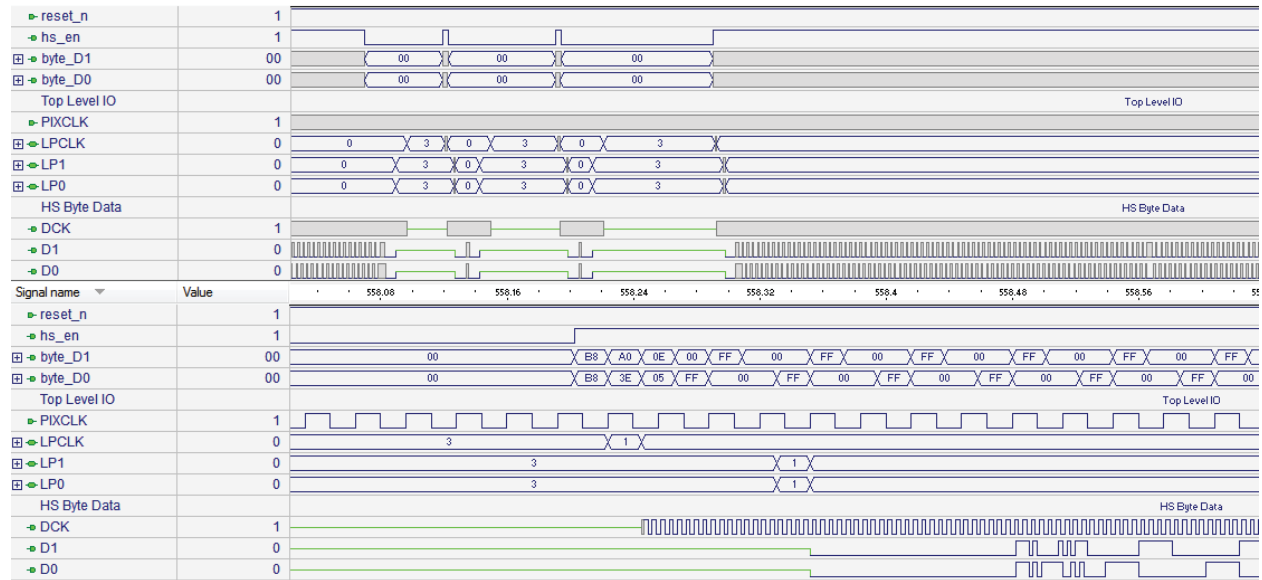




## Functional Simulation

The simulation environment and testbench `Parallel2CSI2_tb_*.v` instantiates the top level design module. The top level design inputs are driven with a generated pattern from the `colorbar_gen` module.

**Figure 9. Simulation Waveforms**

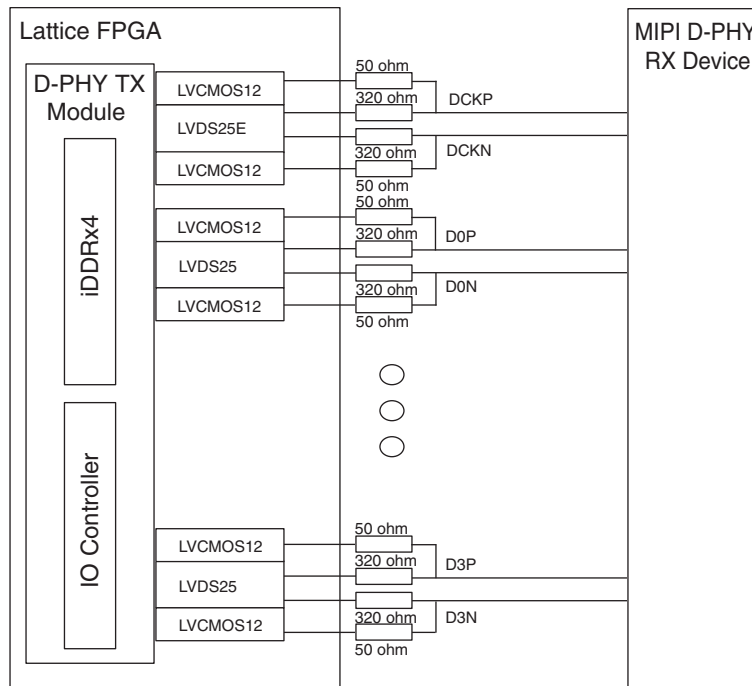


The simulation environment can be accessed by double clicking on the `<name>.spf` script file in Lattice Diamond from the file list. After clicking OK, Aldec ActiveHDL opens to the pop-up windows. Compile the project and initialize the simulation. Add signals to the waveform viewer that are desired to be viewer and run the simulation.

## External Resistor Network Implementation for D-PHY TX

As described in the Lattice RD1182, [MIPI D-PHY Reference IP](#) documentation, an external resistor network is needed to accommodate the LP and HS mode transitioning on the same signal pairs as well as the lower 200 mV common mode voltage during HS clock and data transfers. The resistor network needed for MIPI TX implementations is provided below.

**Figure 10. Unidirectional Transmit HS Mode and Bidirectional LP Mode Interface Implementation**



## Device Pinout and Bank Voltage Requirements

Choosing a proper pinout to interface with another D-PHY device is essential to meet functional and timing requirements.

The following are rules for choosing a proper pinout on MachXO2 devices:

Bank 0 should be used for HS outputs (DCK, D0, D1, D2, D3) with the TX D-PHY IP since these pins utilize oDDRx4 gearbox primitives

- The VCCIO voltage for banks 0 should be 2.5 V
- The HS input clock (DCK) for the RX DPHY IP should use an edge clock on bank 2
- The HS data signals (D0, D1, D2, D3) for the RX and TX DPHY IP's should only use A/B IO pairs
- LP signals (LPCLK, LP0, LP1, LP2, LP3) for RX and TX DPHY IP's can use any other bank
- The VCCIO voltage for the bank containing LP signals (LPCLK, LP0, LP1, LP2, LP3) should be 1.2 V
- When in doubt, run the pinout through Lattice Diamond software can check for errors

With the rules mentioned above a recommend pinout is provided for the most common packages chosen for this IP. For the MachXO2 the cs132bga is the most common package. The pinouts chosen below are pin compatible with MachXO2-1200, MachXO2-2000 and MachXO2-4000 devices.

**Table 6. Recommended TX Pinout and Package**

| Signal    | MachXO2 1200/2000/4000 cs132bga Package |     |
|-----------|---|-----|
| DCK_p     | Bank 0                                  | A7  |
| DCK_n     |   | B7  |
| D0_p      |   | B5  |
| D0_n      |   | C6  |
| D1_p      |   | A2  |
| D1_n      |   | B3  |
| D2_p      |   | A10 |
| D2_n      |   | C11 |
| D3_p      |   | C12 |
| D3_n      |   | A12 |
| LPCLK [1] | Bank 1                                  | E12 |
| LPCLK [0] |   | E14 |
| LP0 [1]   |   | E13 |
| LP0 [0]   |   | F12 |
| LP1 [1]   |   | F13 |
| LP1 [0]   |   | F14 |
| LP2 [1]   |   | G12 |
| LP2 [0]   |   | G14 |
| LP3 [1]   |   | G13 |
| LP3 [0]   |   | H12 |

**Table 7. TX IO Timing**

| Device Family | Speed Grade -4 @ 262Mhz      |                             | Speed Grade -5 @ 315Mhz      |                             | Speed Grade -6 @ 378Mhz      |                             |
|---------------|------------------------------|-----------------------------|------------------------------|-----------------------------|------------------------------|-----------------------------|
| MachXO2™      | Data Valid Before Clock (ps) | Data Valid After Clock (ps) | Data Valid Before Clock (ps) | Data Valid After Clock (ps) | Data Valid Before Clock (ps) | Data Valid After Clock (ps) |
|               | 710                          | 710                         | 570                          | 570                         | 455                          | 455                         |

**Table 8. TX Maximum Operating Frequencies by Configuration<sup>1</sup>**

| Device Family | Configuration                     | Speed Grade -4 (MHz) |          | Speed Grade -5 (MHz) |          | Speed Grade -6 (MHz) |          | Speed Grade -7 (MHz) |          | Speed Grade -8 (MHz) |          |
|---------------|-----------------------------------|----------------------|----------|----------------------|----------|----------------------|----------|----------------------|----------|----------------------|----------|
|               |                                   | PIXCLK               | byte_clk | PIXCLK               | byte_clk | PIXCLK               | byte_clk | PIXCLK               | byte_clk | PIXCLK               | byte_clk |
| ECP5™         | RAW10, 2 Data Lane (LP+HS)- LSE   | —                    | —        | —                    | —        | 205.888              | 127.097  | 244.439              | 152.23   | 267.451              | 187.547  |
|               | RAW10, 2 Data Lanes (LP+HS)- Syn  | —                    | —        | —                    | —        | 220.459              | 135.722  | 258.732              | 149.903  | 291.29               | 140.905  |
| MachXO2       | RAW10, 1 Data Lane (LP+HS)        | 150                  | 97.9     | 164.7                | 110      | 182.5                | 103.3    | 164.7                | 110      | 182.5                | 103.3    |
|               | RAW10, 2 Data Lanes (LP+HS)       | 150                  | 92.5     | 164.7                | 98.367   | 182.5                | 109.158  | 164.7                | 98.367   | 182.5                | 109.158  |
|               | RAW10, 2 Data Lanes (LP+HS) - LSE | 150.015              | 97.704   | 164.69               | 97.733   | 182.5                | 107.365  | 164.69               | 97.733   | 182.5                | 107.365  |
|               | RAW10, 4 Data Lanes (LP+HS)       | 150                  | 94.9     | 164.7                | 100      | 182.5                | 113.2    | 164.7                | 100      | 182.5                | 113.2    |
| MachXO3L      | RAW10, 2 Data Lanes (LP+HS) - LSE | —                    | —        | 164.69               | 106.326  | 182.548              | 99.118   | 164.69               | 106.326  | 182.548              | 99.118   |
|               | RAW10, 2 Data Lanes (LP+HS) - Syn | —                    | —        | 164.69               | 102.881  | 182.548              | 108.542  | 164.69               | 102.881  | 182.548              | 108.542  |

1. The maximum operating frequencies were obtained by post P&R timing analysis. They do not correlate to clocking ratios (obtained from PLL clock equations) used for proper design operation.

## Resource Utilization

The resource utilization tables below represent the device usage in various configurations of the D-PHY IP. Resource utilization was performed on the IP in configurations of 1, 2 and 4 data lanes. For each of these configurations LP mode on the data lanes used was turned on. In addition, HS and LP clock signals were available for each configuration.

**Table 9. TX Resource Utilization**

| Device Family | Configuration                     | Register | LUT  | EBR | PLL | Gearbox | Clock Divider |
|---------------|-----------------------------------|----------|------|-----|-----|---------|---------------|
| ECP5          | RAW10, 2 Data Lanes (LP+HS) - LSE | 627      | 1369 | 3   | 2   | 3       | 1             |
|               | RAW10, 2 Data Lanes (LP+HS) - Syn | 542      | 858  | 3   | 2   | 3       | 1             |
| MachXO2       | RAW10, 1 Data Lanes (LP+HS)       | 217      | 299  | 3   | 1   | 2       | 1             |
|               | RAW10, 2 Data Lanes (LP+HS)       | 272      | 394  | 2   | 1   | 3       | 1             |
|               | RAW10, 4 Data Lanes (LP+HS)       | 345      | 467  | 2   | 1   | 1       | 1             |
| MachXO3L      | RAW10, 2 Data Lanes (LP+HS) - LSE | 447      | 383  | 2   | 1   | 3       | 1             |
|               | RAW10, 2 Data Lanes (LP+HS) - Syn | 272      | 394  | 2   | 1   | 3       | 1             |

## References

- MIPI Alliance Specification for Camera Serial Interface 2 (CSI-2) V1.01
- MIPI Alliance Specification for D-PHY V1.1

## Technical Support Assistance

e-mail: [techsupport@latticesemi.com](mailto:techsupport@latticesemi.com)

Internet: [www.latticesemi.com](http://www.latticesemi.com)

## Revision History

| Date          | Version | Change Summary   |
|---------------|---------|--|
| January 2015  | 01.5    | Added support for ECP5 device family.  |
|               |         | Updated the <a href="#">Packaged Design</a> section. Updated Figure 8, Packaged Design Directory Structure.  |
|               |         | Updated the <a href="#">Device Pinout and Bank Voltage Requirements</a> section. Updated Table 8, TX Maximum Operating Frequencies by Configuration. |
|               |         | Updated the <a href="#">Resource Utilization</a> section. Updated Table 9, TX Resource Utilization.  |
|               |         | Corrected version number on first page footer. Previous version should be 01.4; updated this version to 01.5.  |
| April 2014    | 01.4    | Added support for MachXO3L device family.  |
|               |         | Updated Functional Description section. Revised top level design (top.v) main modules.   |
|               |         | Updated Functional Simulation section. Revised .spf script file name.  |
|               |         | Updated Packaged Design section. Updated Figure 8, Packaged Design Directory Structure.  |
|               |         | Updated the Device Pinout and Bank Voltage Requirements section. Updated Table 8, TX Maximum Operating Frequencies by Configuration.                 |
|               |         | Updated the Resource Utilization section. Updated Table 9, TX Resource Utilization.  |
| March 2014    | 01.3    | Added support for Lattice Diamond 3.1 design software.e  |
| March 2014    | 01.3    | Updated Figure 6, Timing Diagram for LP_HS_DELAY_CNTRL Delay Parameters.   |
| December 2013 | 01.2    | Updated the BYTE_PACKETIZER Module Description section.  |
| August 2013   | 01.1    | Updated Table 8 title to TX Maximum Operating Frequencies by Configuration and added footnote.   |
|               | 01.0    | Initial release.   |